



Product Change Notification / CENO-12ZYBU927

Date:

16-May-2024

Product Category:

Computing Embedded Controllers

PCN Type:

Manufacturing Change

Notification Subject:

CCB 7009 Initial Notice: Qualification of ATP7 as an additional assembly site for MEC5200M-D0-I/LJ, MEC1725N-B0-I/LJ and MEC5200M-D0-I/LJ-TR catalog part numbers (CPN) available in 176L WFBGA (10x10x0.8mm) package.

Affected CPNs:

[CENO-12ZYBU927_Affected_CPN_05162024.pdf](#)

[CENO-12ZYBU927_Affected_CPN_05162024.csv](#)

Notification Text:

PCN Status:Initial Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of ATP7 as an additional assembly site for MEC5200M-D0-I/LJ, MEC1725N-B0-I/LJ and MEC5200M-D0-I/LJ-TR catalog part numbers (CPN) available in 176L WFBGA (10x10x0.8mm) package.

Pre and Post Change Summary:

	Pre Change		Post Change		
Assembly Site	ASE Inc. (ASE)	Amkor Assembly & Test (Shanghai) Co., LTD (ANAC)	ASE Inc. (ASE)	Amkor Assembly & Test (Shanghai) Co., LTD (ANAC)	Amkor Technology Philippines (P3/P4), INC. (ATP7)
Wire Material	CuPd	CuPdAu	CuPd	CuPdAu	CuPdAu
Die Attach Material 1	ATB-125	HR-9004	ATB-125	HR-9004	EM-760L2-P
Die Attach Material 2	FH-SC13-HR51 04	HR-9004	FH-SC13-HR51 04	HR-9004	EM-760L2-P
Molding Compound Material	KE-G1250NAS	G750E	KE-G1250NAS	G750E	G770FE
Substrate Core Material	CCL-HL832NS	HL832NXA	CCL-HL832NS	HL832NXA	HL832NXA
Core Thickness	60+/-15	60+/-20	60+/-15	60+/-20	60+/-20
SM Material	PSR4000 AUS308	AUS320	PSR4000 AUS308	AUS320	AUS320
Solder Ball Material	SAC105	SAC105	SAC105	SAC105	SAC105

Impacts to Data Sheet:None

Change ImpactNone

Reason for Change:To improve on-time delivery performance by qualifying ATP7 as an additional assembly site.

Change Implementation Status:In Progress

Estimated Qualification Completion Date:October 2024

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	May 2024					>	October 2024				
Workweek	1 8	1 9	2 0	2 1	2 2		40	41	42	43	44
Initial PCN Issue Date			x								
Qual Report Availability								x			
Final PCN Issue Date								x			

Method to Identify Change:Traceability code

Qualification Plan:Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History:May 16, 2024: Issued initial notification

The change described in this PCN does not alter Microchip’s current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_CENO-12ZYBU927_Qual Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

CENO-12ZYBU927 - CCB 7009 Initial Notice: Qualification of ATP7 as an additional assembly site for MEC5200M-D0-I/LJ, MEC1725N-B0-I/LJ and MEC5200M-D0-I/LJ-TR catalog part numbers (CPN) available in 176L WFBGA (10x10x0.8mm) package.

Affected Catalog Part Numbers (CPN)

MEC5200M-D0-I/LJ

MEC5200M-D0-I/LJ-TR

MEC1725N-B0-I/LJ